
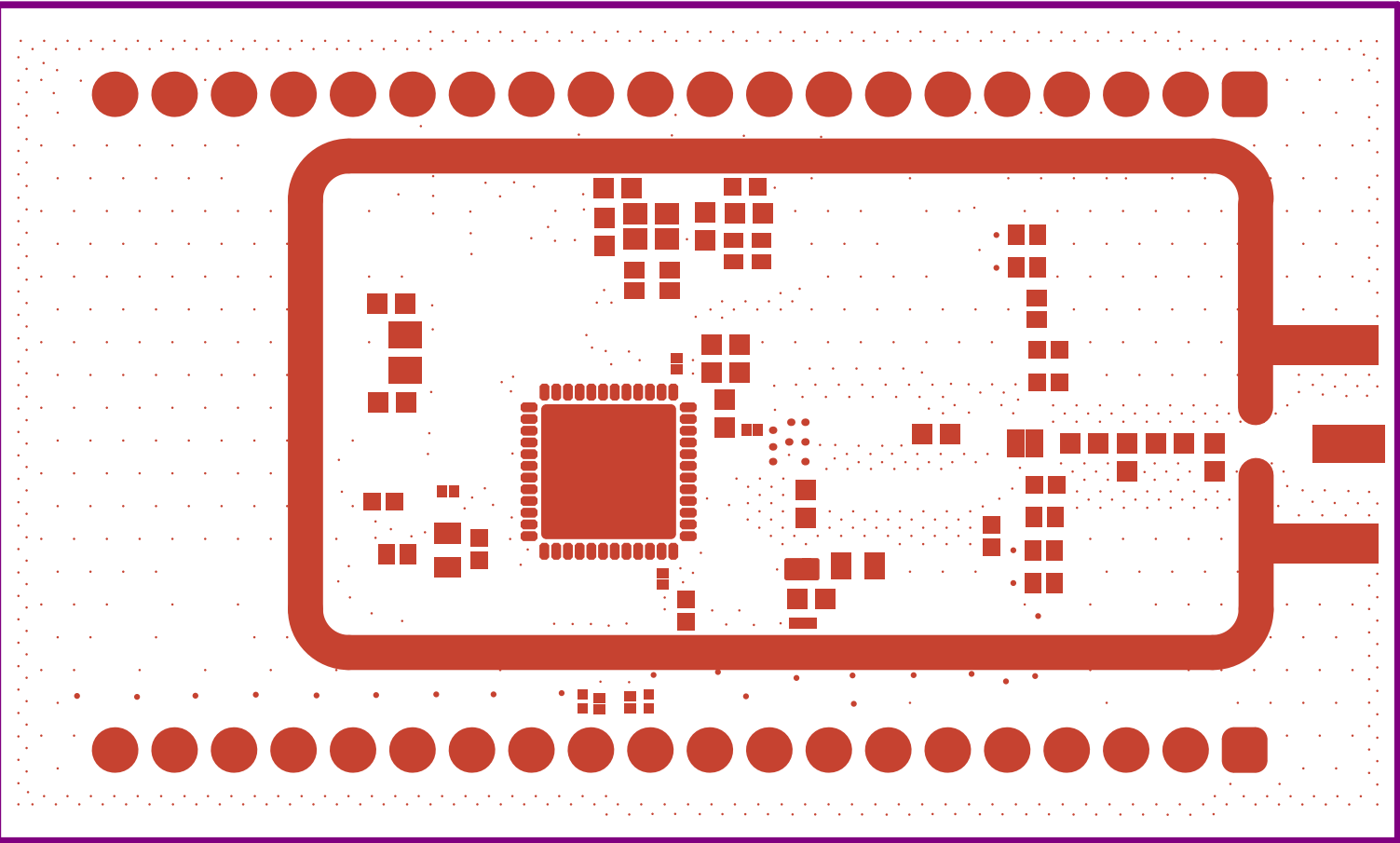

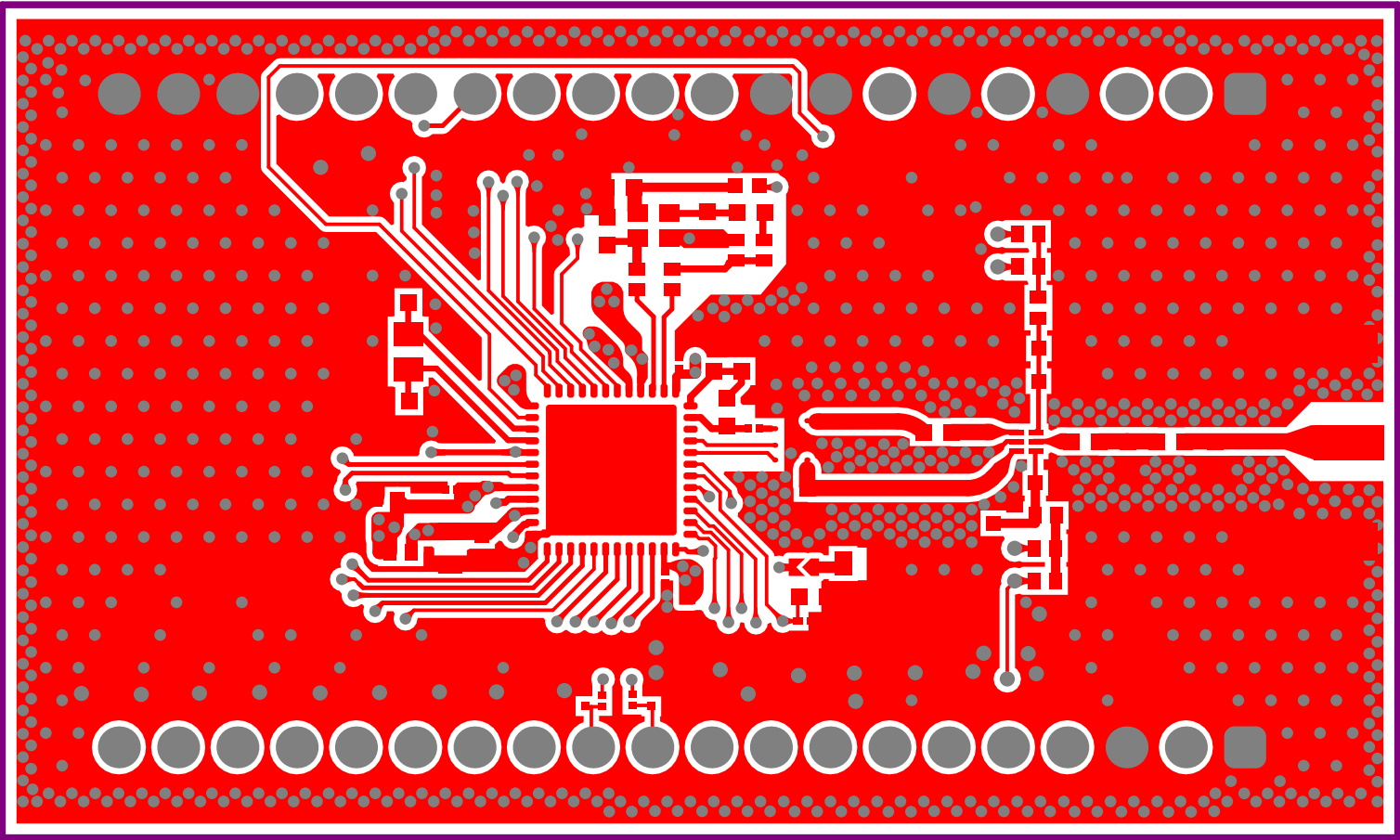



Project: STM32WL_QFN48_IPD_2Layers_HighPower		
Layer: Top Overlay	Gerber: .GTO	
Variant: [No Variations]	Ref: MB1874_HP	
Date: 20/07/2022	Rev: A	

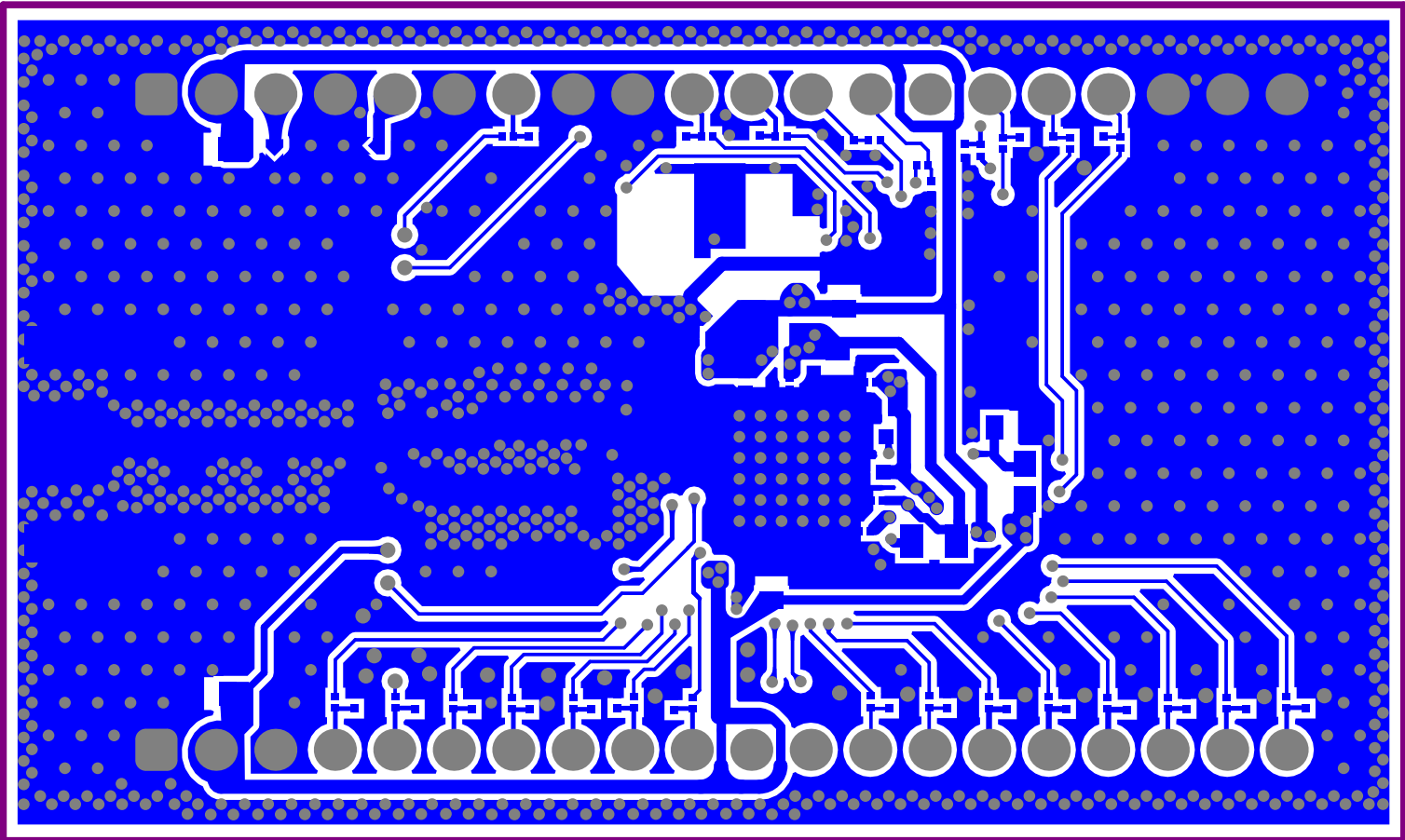


Project: STM32WL_QFN48_IPD_2Layers_HighPower		
Layer: Top Solder	Gerber: .GTS	
Variant: [No Variations]	Ref: MB1874_HP	
Date: 20/07/2022	Rev: A	



Layer	Name	Material	Thickness	Constant
	Top Overlay			
	Top Solder	Solder Resist	1.18mil	3.5
1	Top Layer		1.38mil	
	Dielectric 1	FR-4	27.95mil	5
2	Bottom Layer		1.38mil	
	Bottom Solder	Solder Resist	1.18mil	3.5
	Bottom Overlay			

Project: STM32WL_QFN48_IPD_2Layers_HighPower		
Layer: Top Layer	Gerber: .GTL	
Variant: [No Variations]	Ref: MB1874_HP	
Date: 20/07/2022	Rev: A	



Project: STM32WL_QFN48_IPD_2Layers_HighPower

Layer: Bottom Layer

Gerber:.GBL

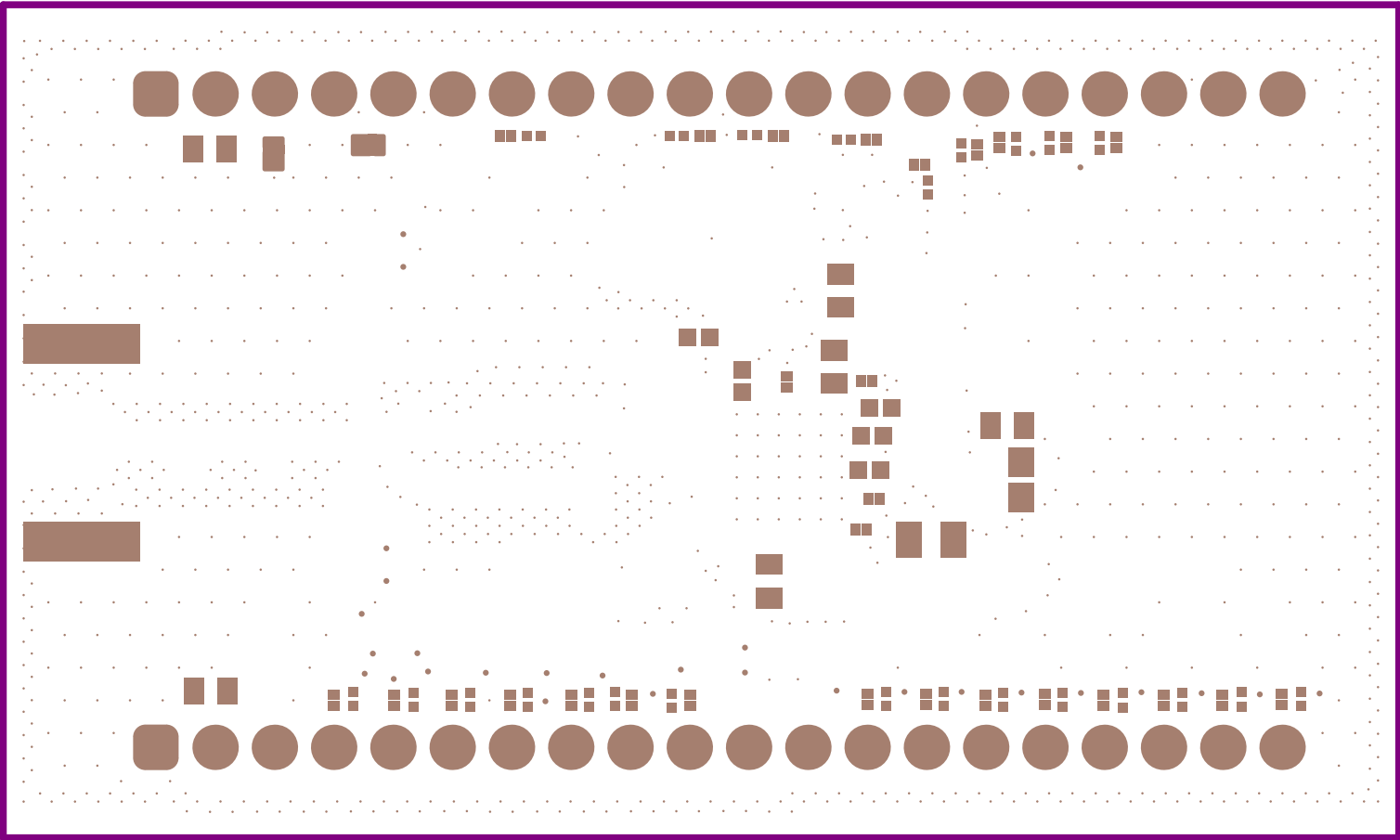
Variant: [No Variations]

Ref: MB1874_HP

Date: 20/07/2022

Rev: A





Project: STM32WL_QFN48_IPD_2Layers_HighPower

Layer: Bottom Solder

Gerber:.GBS

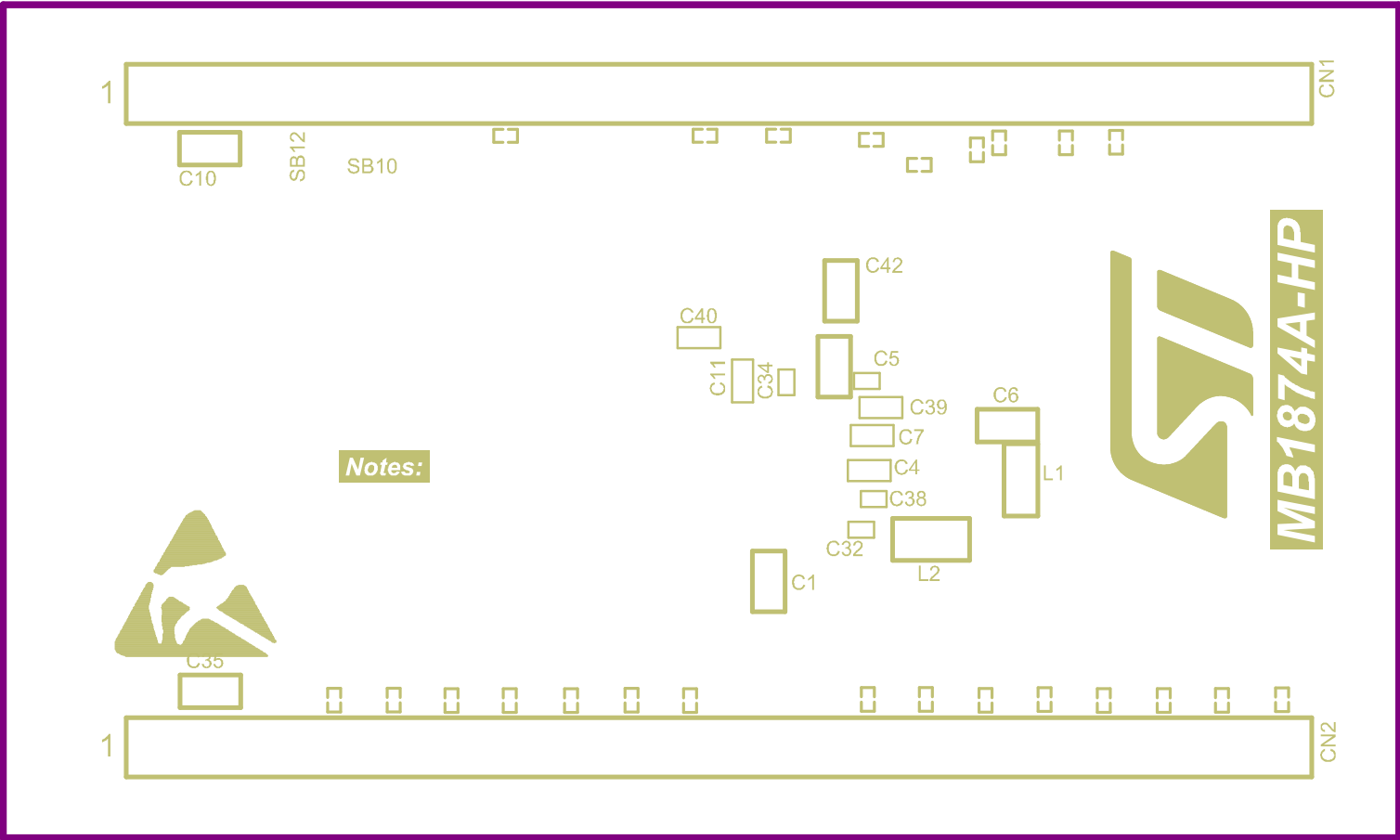
Variant: [No Variations]


Ref: MB1874_HP

Date: 20/07/2022

Rev: A





Project: STM32WL_QFN48_IPD_2Layers_HighPower		
Layer: Bottom Overlay	Gerber: GBO	
Variant: [No Variations]	Ref: MB1874_HP	
Date: 20/07/2022	Rev: A	

Symbol	Count	Hole Size	Plated	Hole Type	Drill Layer Pair	Via/Pad	Pad Shape	Template
□	40	1.000mm (39.37mil)	PTH	Round	Top Layer - Bottom Layer	Pad	(Mixed)	(Mixed)
○	300	0.200mm (7.87mil)	PTH	Round	Top Layer - Bottom Layer	Via	Rounded	v50h20
▽	747	0.200mm (7.87mil)	PTH	Round	Top Layer - Bottom Layer	Via	Rounded	(Mixed)
	1087 Total							

PCB SPECIFICATIONS :

A. MATERIAL :

B. MATERIAL FAMILY :

C. SOLDERMASK COLOR :

D. SILKSCREEN COLOR :

E. SURFACE FINISH :

F. IMPEDANCE CONTROL :

G. THROUGH VIA :

H. STACK-UP :

FR-4

N/A

☒ GREEN

☐ BLUE

☐ RED

☐ BLACK

☒ WHITE

☐ YELLOW

☐ BLACK

☒ ENIG

☐ IMMERSION SILVER

☐ IMMERSION TIN

☐ HASL

☐ HASL (PB-FREE)

☐ GOLDEN FINGER

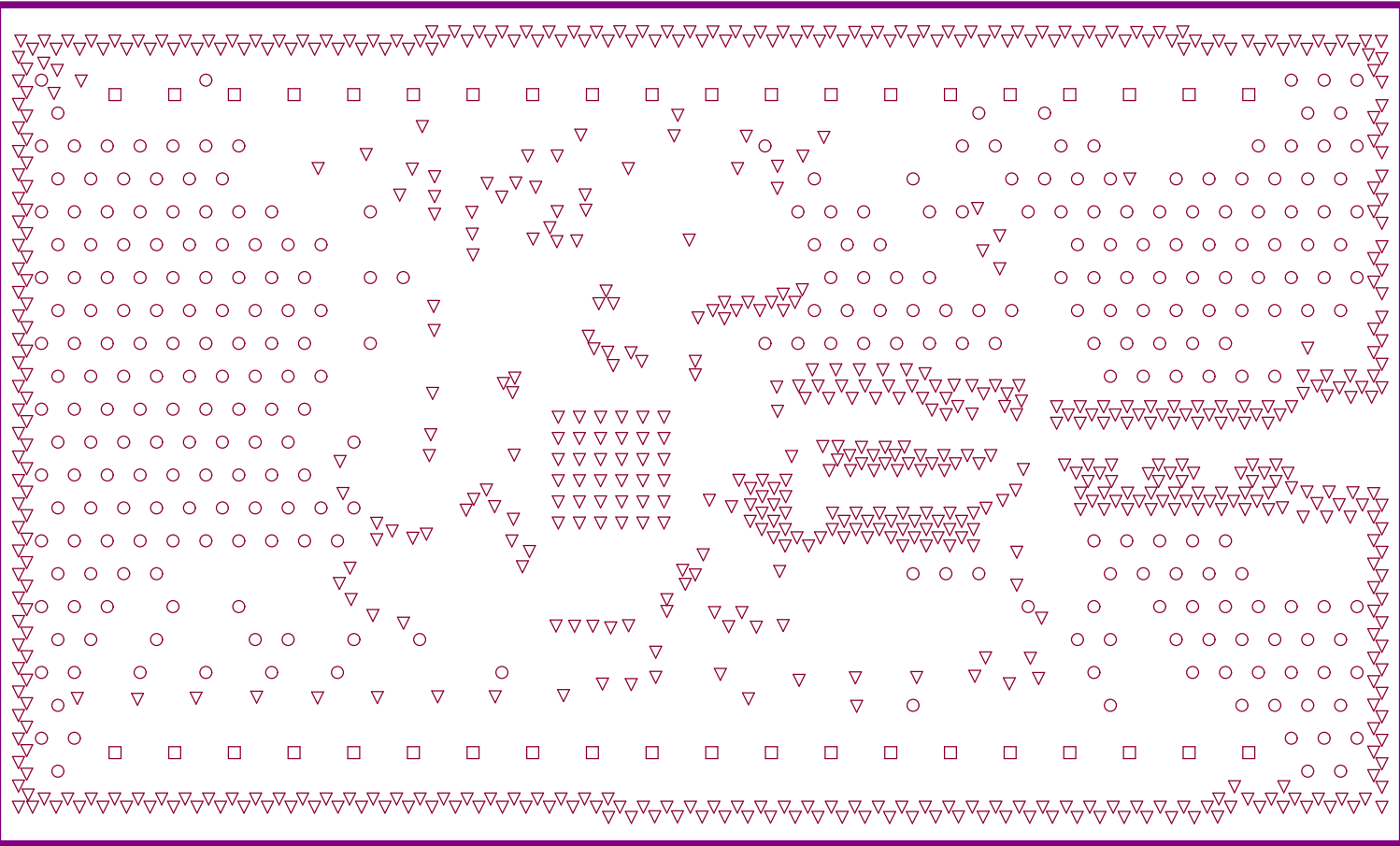
☐ NO


☒ YES (SEE IMPEDANCE TABLE FOR DETAIL INFORMATION)

PLUG THE VIAS WHICH ARE COVERED WITH SOLDERMASK ONE OR TWO SIDE.

PLUG MATERIAL : ☒ SOLDERMASK ☐ NON-CONDUCTIVE EPOXY.

SEE LAYER STACK-UP SEQUENCE FOR OVERALL THICKNESS.



Project: STM32WL_QFN48_IPD_2Layers_HighPower		
Layer: Drill Drawing	Gerber: .DRL	
Variant: [No Variations]	Ref: MB1874_HP	
Date: 20/07/2022	Rev: A	

IMPEDANCE TABLE					
LAYER	TRACE mils	SPACING mils	IMPEDANCE (Single ended)	IMPEDANCE (Differentiel)	TOL.
TOP	27.56	9.84	50 ohm	NA	+/- 10%